## **EAST Search History**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	348	polysilicon adj contact and via and implantation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/23 16:37
S2	166	polysilicon adj contact and via and implantation and (interconnect or inter adj connect or inter-connect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/02 10:20
S3	311	juengling.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/02 10:20
S4	23	cmos and juengling.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/02 10:22
S5	3	("5015594"   "5022958"   "5112765").PN.	USPAT	OR	ON	2004/04/02 10:22
S6	179	doped adj polysilicon adj contacts	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/04/02 10:23
S7	8	(("5479048") or ("4874719") or ("4948756") or ("5666007")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/04/02 11:01
S8	7	"4948756".URPN.	USPAT	OR	ON	2004/04/02 10:53
S9	15	"5358903".URPN.	USPAT	OR	ON	2004/04/02 10:56
S10	2	("5506172").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/04/02 11:01
S11	8	("4176003"   "4178674"   "4240196"   "4394406"   "5126231"   "5162259"   "5292676"   "5326713").PN.	USPAT	OR	ON	2004/04/02 11:10

## **EAST Search History**

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S12	2284	(438/586).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/23 15:35
S13	42	grinding adj machine and semiconductor adj wafer and detection	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/23 15:39
S14	282	(438/647).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/23 16:25
S15	7936	(substate and first adj polycrystalline adj silicon and lowest and upper and second polycrystalline adj silicon).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/23 16:26
S16	0	(substate and first adj polycrystalline adj silicon and lowest and upper and second polycrystalline adj silicon and highest and distal).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/23 16:27
S17	4	257/e21.585	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/23 16:38

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